

NVH040N65S3F Datasheet



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DiGi Electronics Part Number NVH040N65S3F-DG

Manufacturer onsemi

Manufacturer Product Number NVH040N65S3F

Description SF3 FRFET AUTO 40MOHM TO-247

Detailed Description N-Channel 650 V 65A (Tc) 446W (Tc) Through Hole

TO-247-



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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
NVH040N65S3F	onsemi
Series:	Product Status:
SuperFET® III	Active
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
650 V	65A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
10V	40mOhm @ 32.5A, 10V
Vgs(th) (Max) @ Id:	Gate Charge (Qg) (Max) @ Vgs:
5V @ 2.1mA	153 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±30V	5875 pF @ 400 V
FET Feature:	Power Dissipation (Max):
	446W (Tc)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Through Hole
Supplier Device Package:	Package / Case:
TO-247-3	TO-247-3

Environmental & Export classification

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	Not Applicable
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	

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MOSFET – Power, N-Channel, SUPERFET[®] III, FRFET[®] 650 V, 65 A, 40 mΩ

NVH040N65S3F

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

Features

- 700 V @ $T_J = 150$ °C
- Typ. $R_{DS(on)} = 33.8 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 153 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 1333 pF)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

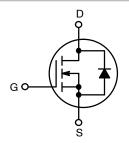
- Automotive On Board Charger HEV-EV
- Automotive DC/DC converter for HEV-EV



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V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	40 mΩ @ 10 V	65 A

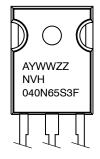


POWER MOSFET



TO-247-3LD CASE 340CK

MARKING DIAGRAM



NVH040N65S3F = 3

YWW

Specific Device CodeAssembly Plant CodeData Code (Year & Week)

ZZ = Lot

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$, Unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{DSS}	Drain to Source Voltage	е		V
V_{GSS}	Gate to Source Voltage	- DC	±30	V
		- AC (f > 1 Hz)	±30	
I _D	Drain Current	– Continuous (T _C = 25°C)	65	Α
		– Continuous (T _C = 100°C)	45	
I _{DM}	Drain Current	- Pulsed (Note 1)	162.5	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	ingle Pulsed Avalanche Energy (Note 2)		mJ
E _{AR}	Repetitive Avalanche Energy (Note 1)		4.46	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	Peak Diode Recovery dv/dt (Note 3)		
P_{D}	Power Dissipation	Power Dissipation $(T_C = 25^{\circ}C)$		W
		- Derate Above 25°C	3.57	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse–width limited by maximum junction temperature.

2. $I_{AS} = 9 \text{ A}$, $R_G = 25 \Omega$, starting $T_J = 25^{\circ}C$.

3. $I_{SD} \le 32.5 \text{ A}$, $di/dt \le 200 \text{ A}/\mu\text{s}$, $V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}C$.

THERMAL CHARACTERISTICS

Symbol Parameter		Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.28	°C/W
$R_{\theta JA}$	R _{θJA} Thermal Resistance, Junction to Ambient, Max.		

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Shipping (Qty / Packing)
NVH040N65S3F	NVH040N65S3F	TO-247 G03	Tube	30 Units / Tube

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACT	ERISTICS					•
BV _{DSS}	Drain to Source Breakdown Voltage	V _{GS} = 0 V, I _D = 1 mA, T _J = 25°C	650	_	-	V
		V _{GS} = 0 V, I _D = 10 mA, T _J = 150°C	700	_	-	V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	_	0.64	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	_	_	10	μΑ
		V _{DS} = 520 V, T _C = 125°C	_	103	-	
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	-	_	±100	nA
ON CHARACTE	RISTICS			•	•	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 2.1 \text{ mA}$	3.0	_	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 32.5 A	-	33.8	40	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 32.5 A	-	40	-	S
DYNAMIC CHAI	RACTERISTICS			•	•	
C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 1 MHz	-	5875	-	pF
C _{oss}	Output Capacitance		-	140	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	1333	-	pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	241	-	pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 400 V, I _D = 32.5 A, V _{GS} = 10 V	-	153	-	nC
Q _{gs}	Gate to Source Gate Charge	(Note 4)	-	51	-	nC
Q_{gd}	Gate to Drain "Miller" Charge]	-	61	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1.9	-	Ω
SWITCHING CH	ARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, I_D = 32.5 \text{ A}, V_{GS} = 10 \text{ V}$	-	41	-	ns
t _r	Turn-On Rise Time	$R_g = 2.2 \Omega$ (Note 4)	-	53	-	ns
t _{d(off)}	Turn-Off Delay Time		-	96	-	ns
t _f	Turn-Off Fall Time		-	28	-	ns
SOURCE-DRAII	N DIODE CHARACTERISTICS					•
I _S	Maximum Continuous Source to Drain Diode Forward Current		-	_	65	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		-	_	162.5	Α
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 32.5 A	_	_	1.3	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 32.5 A,	_	159	-	ns
Q _{rr}	Reverse Recovery Charge	dl _F /dt = 100 A/μs	-	840	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS

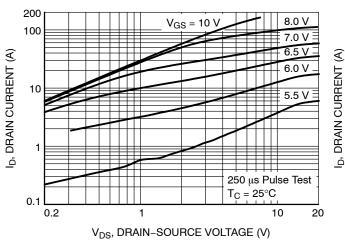


Figure 1. On-Region Characteristics

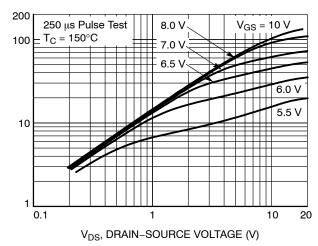


Figure 2. On-Region Characteristics

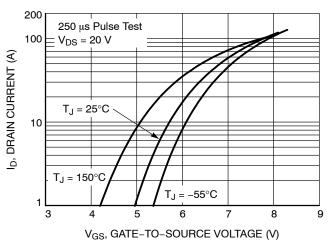


Figure 3. Transfer Characteristics

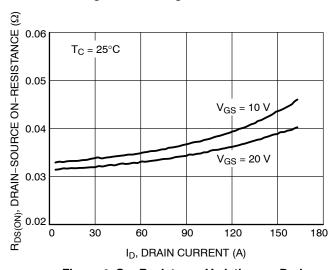


Figure 4. On–Resistance Variation vs. Drain Current and Gate Voltage

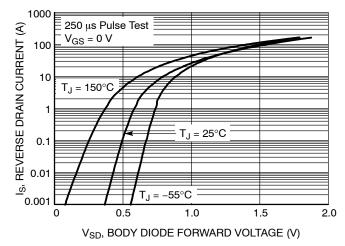


Figure 5. Body Diode Forward Voltage Variation vs. Source Current and Temperature

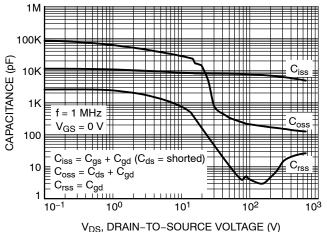
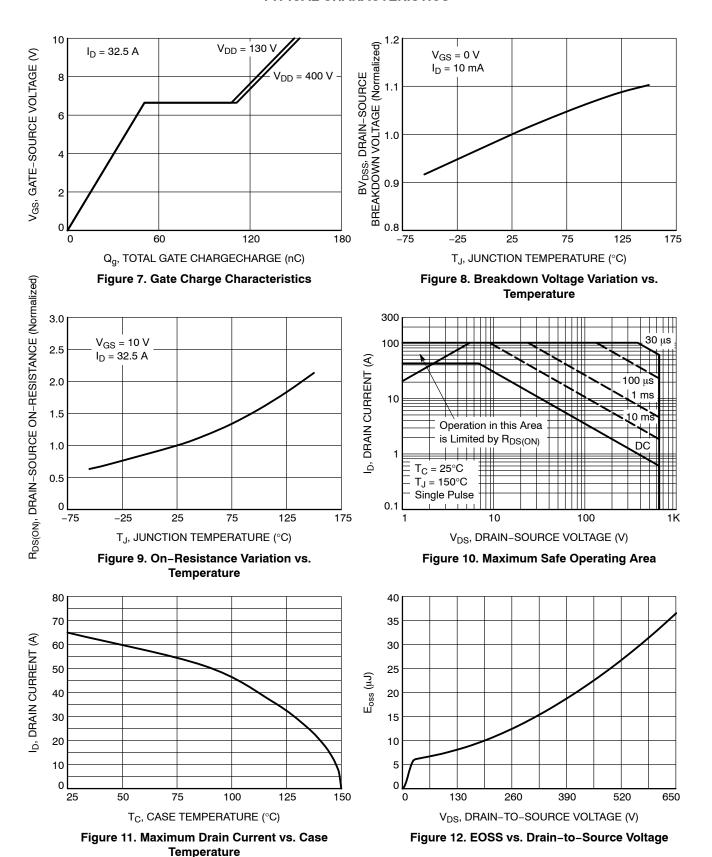


Figure 6. Capacitance Characteristics

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

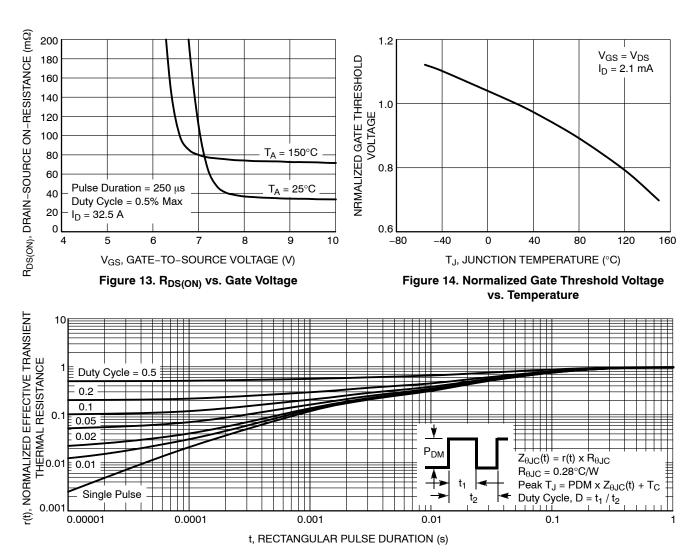


Figure 15. Transient Thermal Response Curve

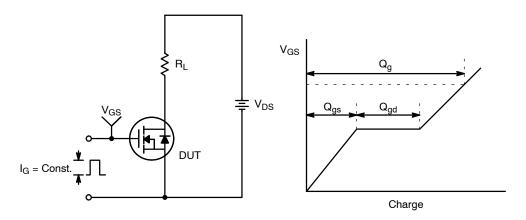


Figure 16. Gate Charge Test Circuit & Waveform

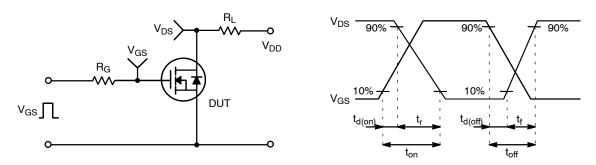


Figure 17. Resistive Switching Test Circuit & Waveforms

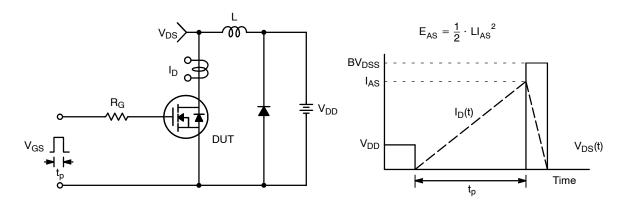
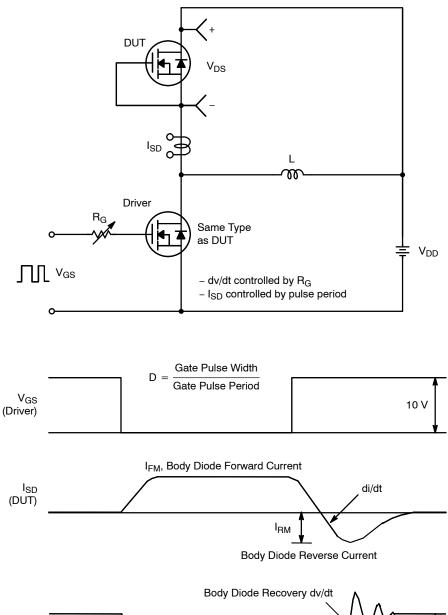


Figure 18. Unclamped Inductive Switching Test Circuit & Waveforms



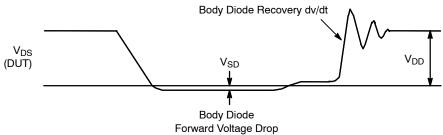
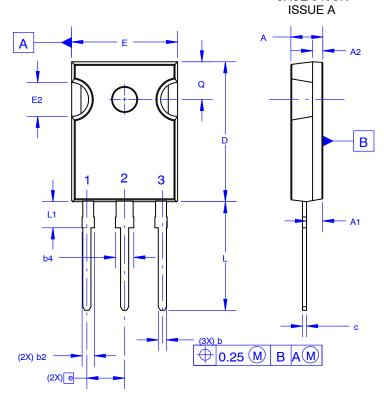


Figure 19. Peak Diode Recovery dv/dt Test Circuit & Waveforms

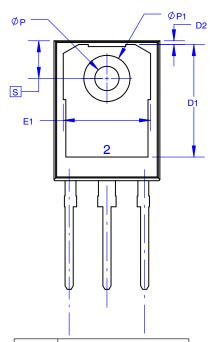
PACKAGE DIMENSIONS

TO-247-3LD SHORT LEAD CASE 340CK



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS		
DIIVI	MIN	NOM	MAX
Α	4.58	4.70	4.82
A1	2.20	2.40	2.60
A2	1.40	1.50	1.60
b	1.17	1.26	1.35
b2	1.53	1.65	1.77
b4	2.42	2.54	2.66
С	0.51	0.61	0.71
D	20.32	20.57	20.82
D1	13.08	~	~
D2	0.51	0.93	1.35
Е	15.37	15.62	15.87
E1	12.81	~	~
E2	4.96	5.08	5.20
е	~	5.56	~
L	15.75	16.00	16.25
L1	3.69	3.81	3.93
ØΡ	3.51	3.58	3.65
Ø P1	6.60	6.80	7.00
Q	5.34	5.46	5.58
S	5.34	5.46	5.58

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